

# MINIMIZING POWER AMPLIFIER MEMORY EFFECTS

ALLEN KATZ\* AND MARC FRANCO

\*The College Of New Jersey



Linearizer Technology, Inc. <sup>TM</sup>

3 Nami Lane, Unit C-9 / Hamilton, NJ 08619 / Tel: 609.584.8424 / Fax: 609.631.0177

[www.lintech.com](http://www.lintech.com)

# Introduction

- Memory Effects (ME) are changes in a Power Amplifier's (PA) non-linear characteristics resulting from the past history of the input signal.

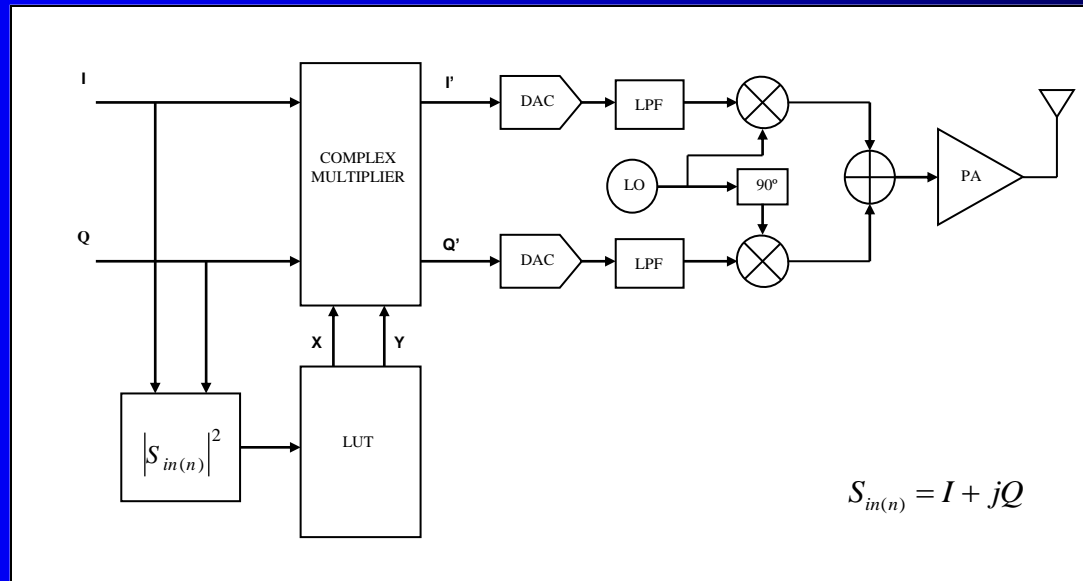
$$V_o = f(V_{in}, \text{time})$$

- Standard predistortion linearization depends on a stable non-linear response, and is particularly degraded by memory effects
- Techniques to reduce PA memory effects will be presented

# OUTLINE

- Why minimize memory effects in PA's ?
- Discuss different sources of ME and how to suppress them
  - Frequency ME
  - Drain/collector ME
  - Gate/base ME
  - Device related ME
  - Thermal ME
- Summarize and conclude

# BASIC DSP PREDISTORTION (PD) LINEARIZER

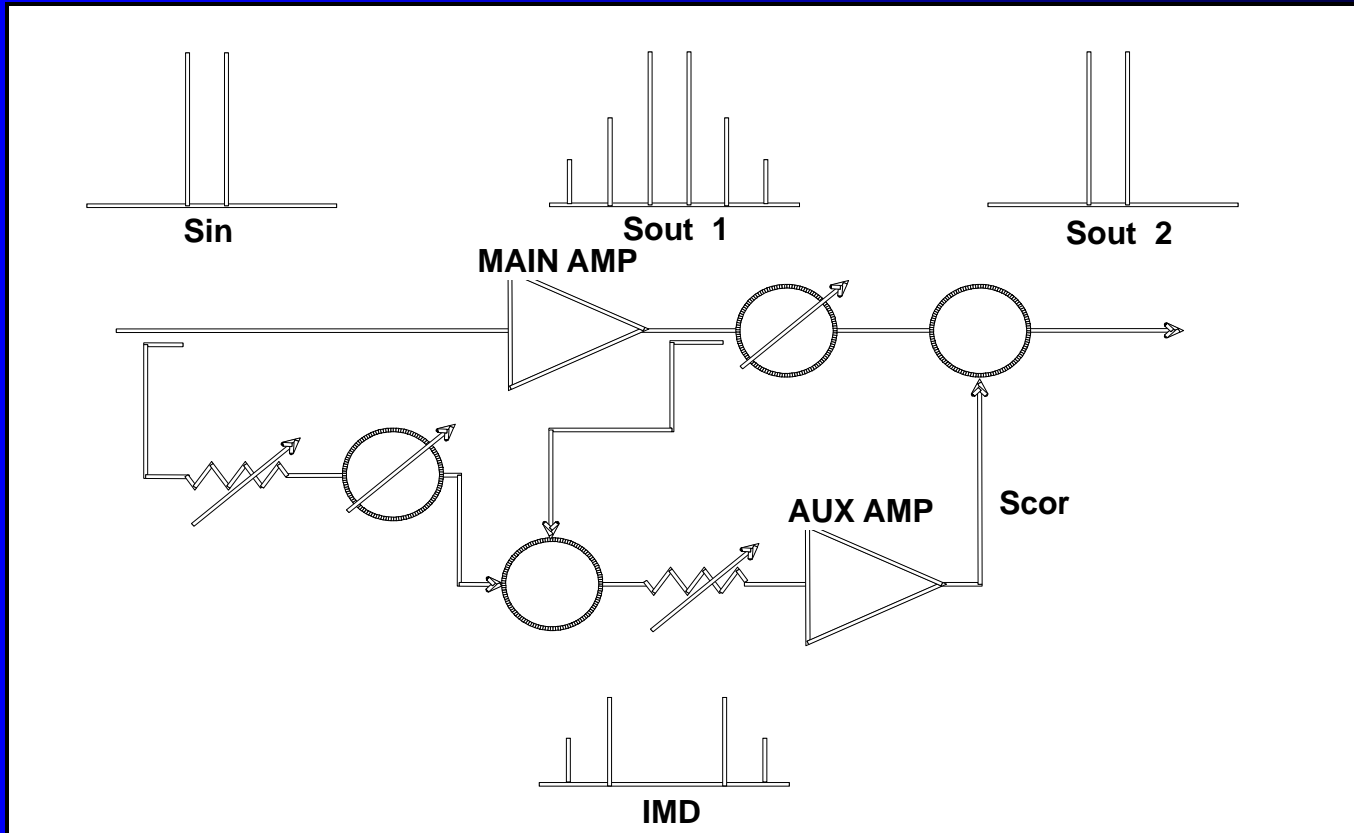


- Every input level has a corresponding output level
- Correction (mag & phase) in look up tables (LUT) depends on input level
- LUT often adaptively updated for slow changes over time

# BASIC DSP PREDISTORTION LINEARIZER

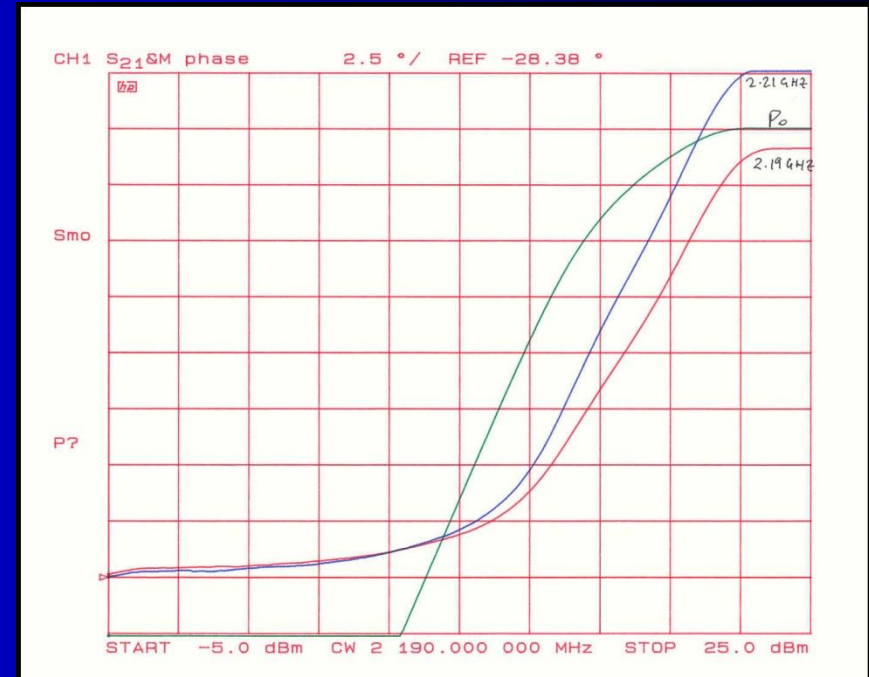
- Memory Effects cause correction to depend on recent past
- If correction depends on additional parameters, system can become very complex (huge multi dimensional LUTs, limited processing time and bandwidth)
- Feedback is not a solution because amplifier time delay limits maximum bandwidth
- Best solution is to minimize ME by PA design

# FEEDFORWARD LINEARIZATION



Automatically corrects for memory effects, but is more complex and less efficient than predistortion

# FREQUENCY MEMORY EFFECTS



**GAIN VS. INPUT POWER IS  
AFFECTED BY FREQUENCY**

**PHASE VS. INPUT POWER IS  
AFFECTED BY FREQUENCY**

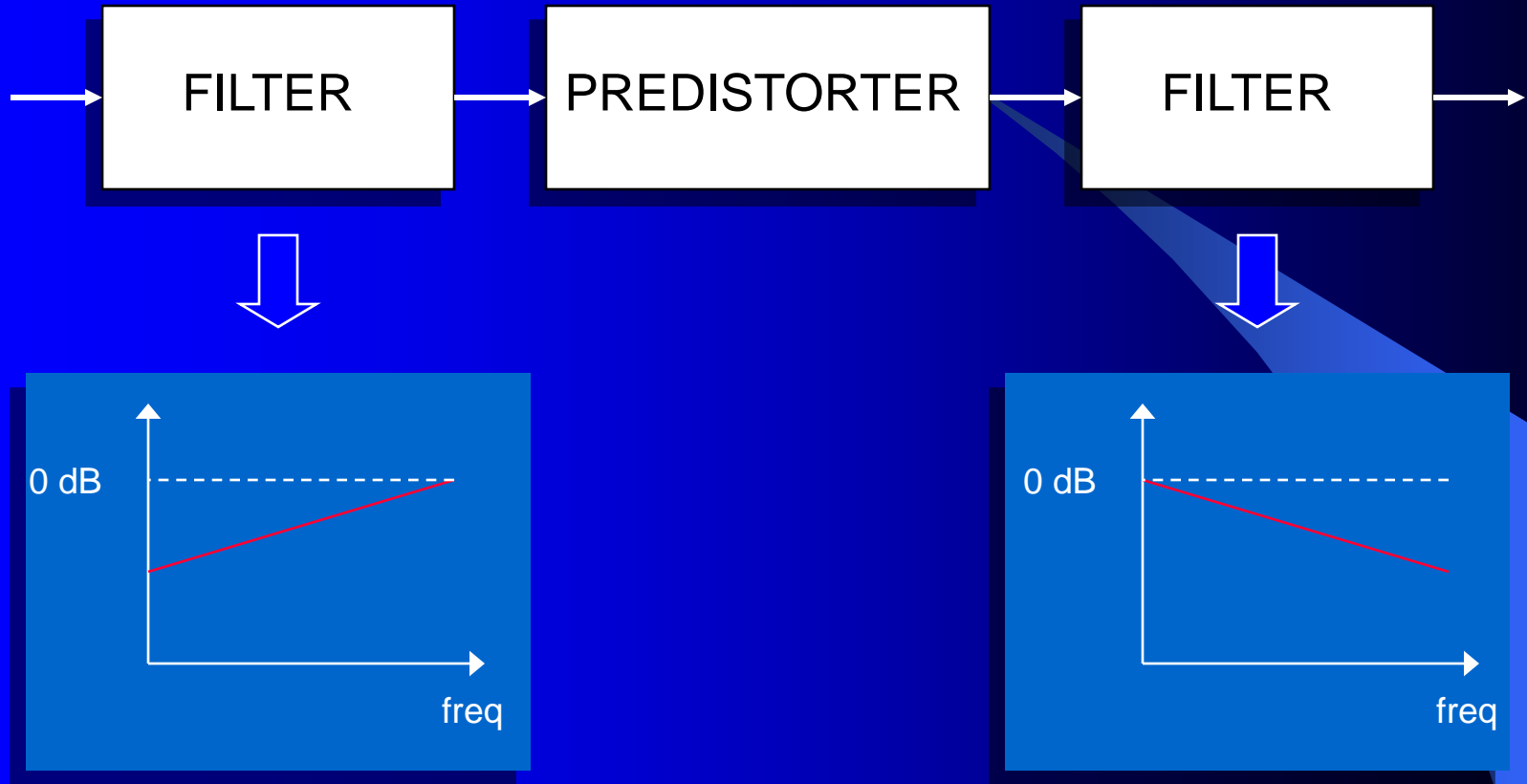
- Standard predistorter look-up tables have the same correction for every frequency
- Real PA non-linearities do change with frequency

# FREQUENCY MEMORY EFFECTS

- No easy circuit solution for wideband signals
- Design PA for as wide a bandwidth as possible
- Avoid frequency selective components
- Achieve low SWR at input and output and maintain it low across full band of interest
- Must equalize small signal gain and phase to achieve good wideband performance
- Adaptive techniques can correct for frequency changes of limited bandwidth signals

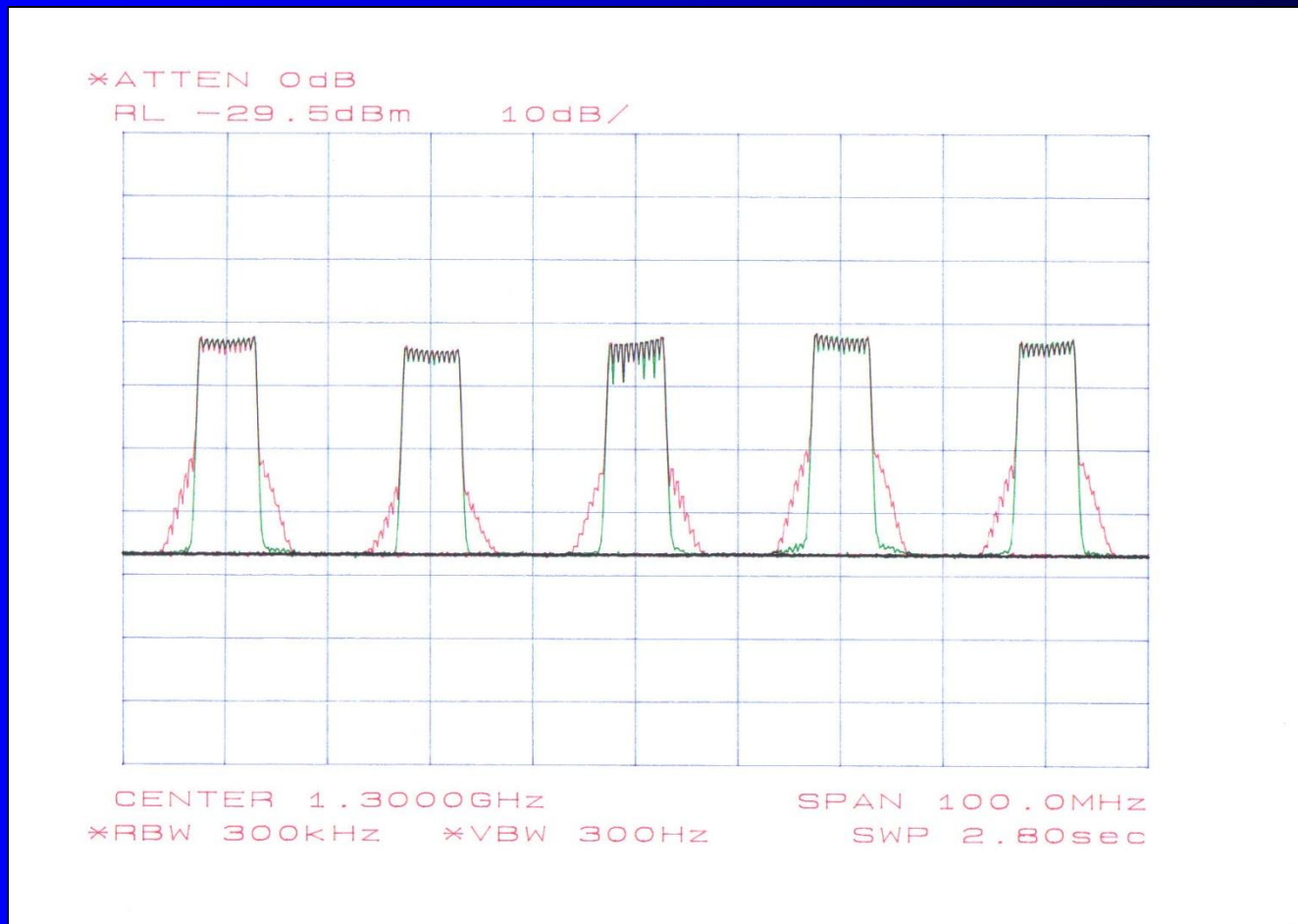


# FREQUENCY MEMORY EFFECTS



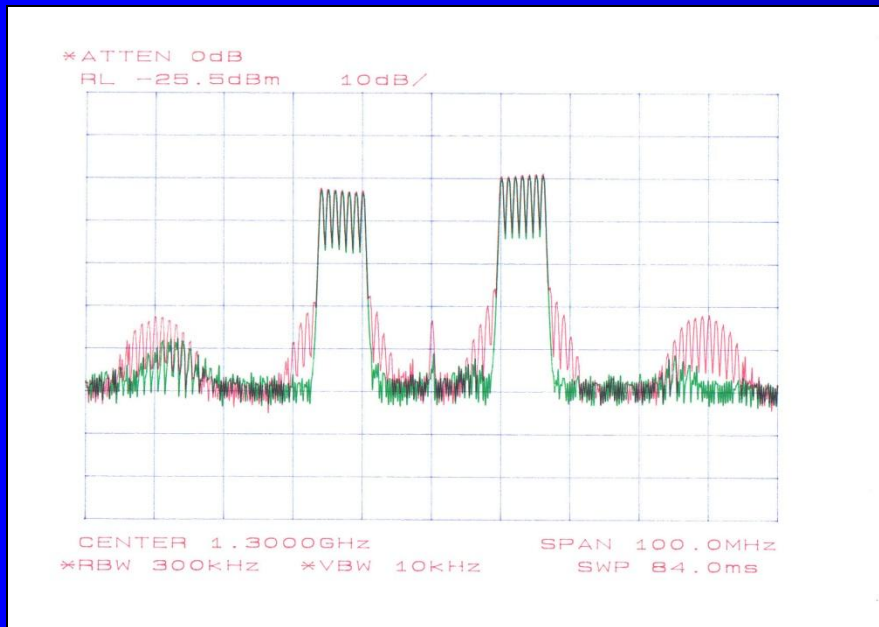
**Proposed architecture for reducing memory effects produced by frequency sensitivity**

# FREQUENCY MEMORY EFFECTS

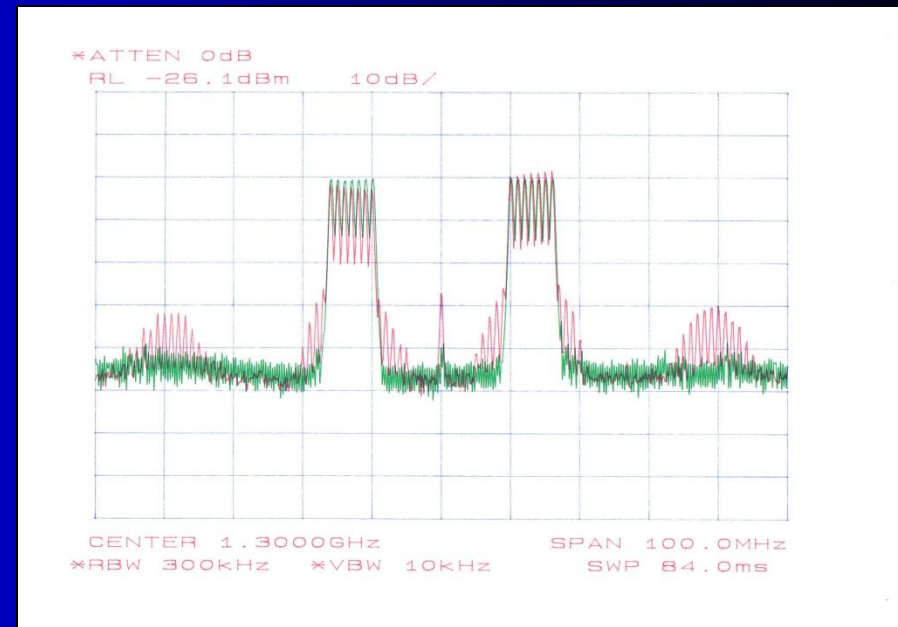


**Digital linearization across 100 MHz using filters to correct for frequency memory effects**

# FREQUENCY MEMORY EFFECTS



**Digital linearization across 100 MHz  
without memory effects  
correction**

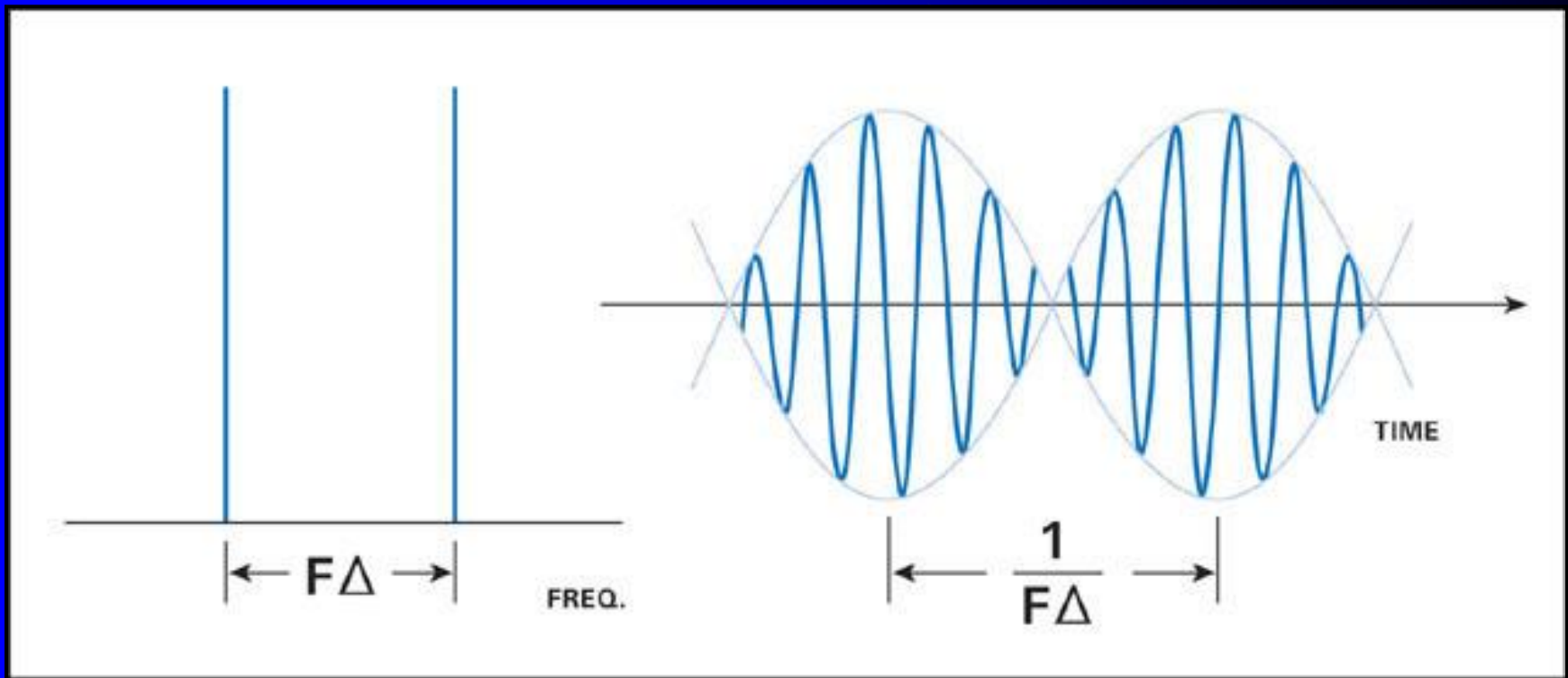


**Digital linearization across 100 MHz  
with memory effects correction**

# DRAIN/COLLECTOR MEMORY EFFECTS

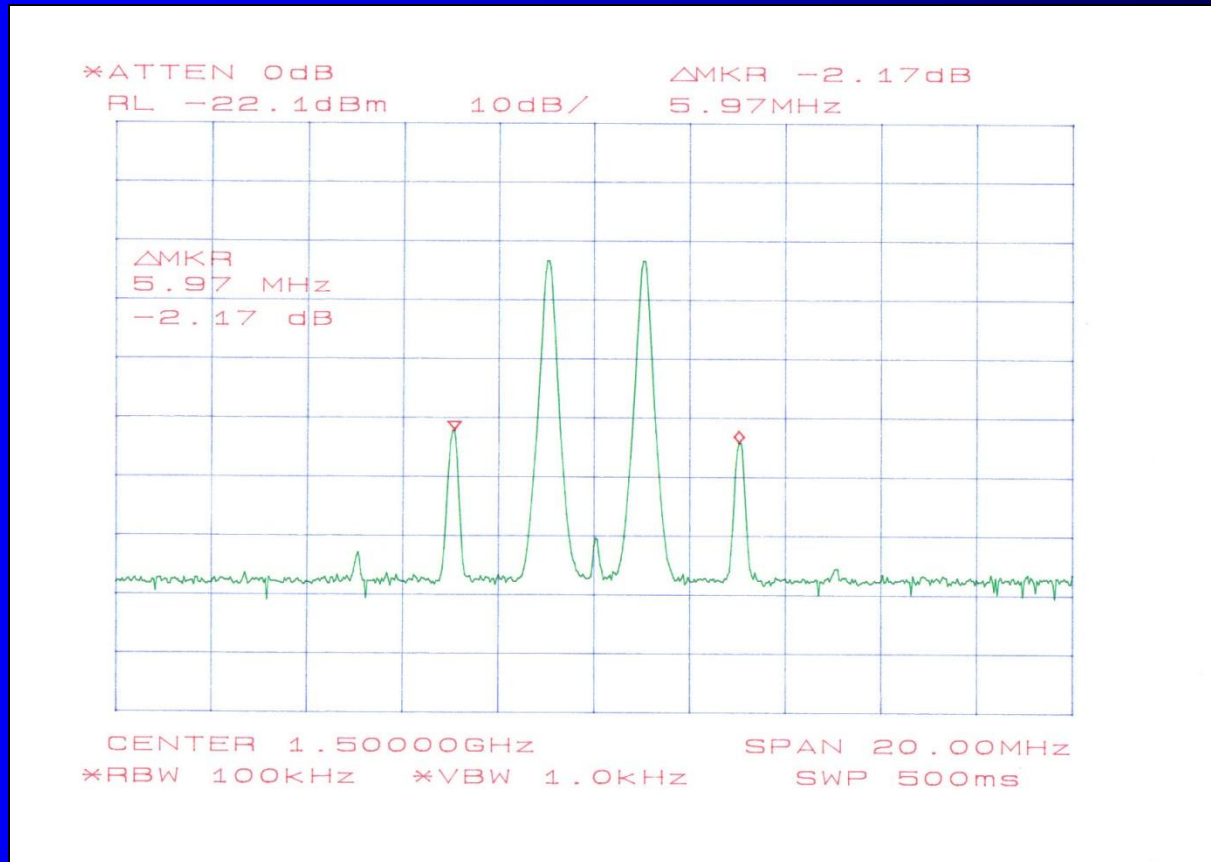
- The major contributor to ME in many PAs is change in drain (or collector) voltage due to non-zero bias/power supply impedance
- All PAs must isolate the RF (i.e. microwave) signal from the dc power supply
- The drain isolation circuit must have a low impedance at the signal's baseband (envelope) frequencies, to avoid envelope dependent voltage changes at the drain
- Even class A PAs will have an envelope dependent voltage change, although the problem becomes worse as a PA's bias moves toward class B

# DRAIN/COLLECTOR MEMORY EFFECTS



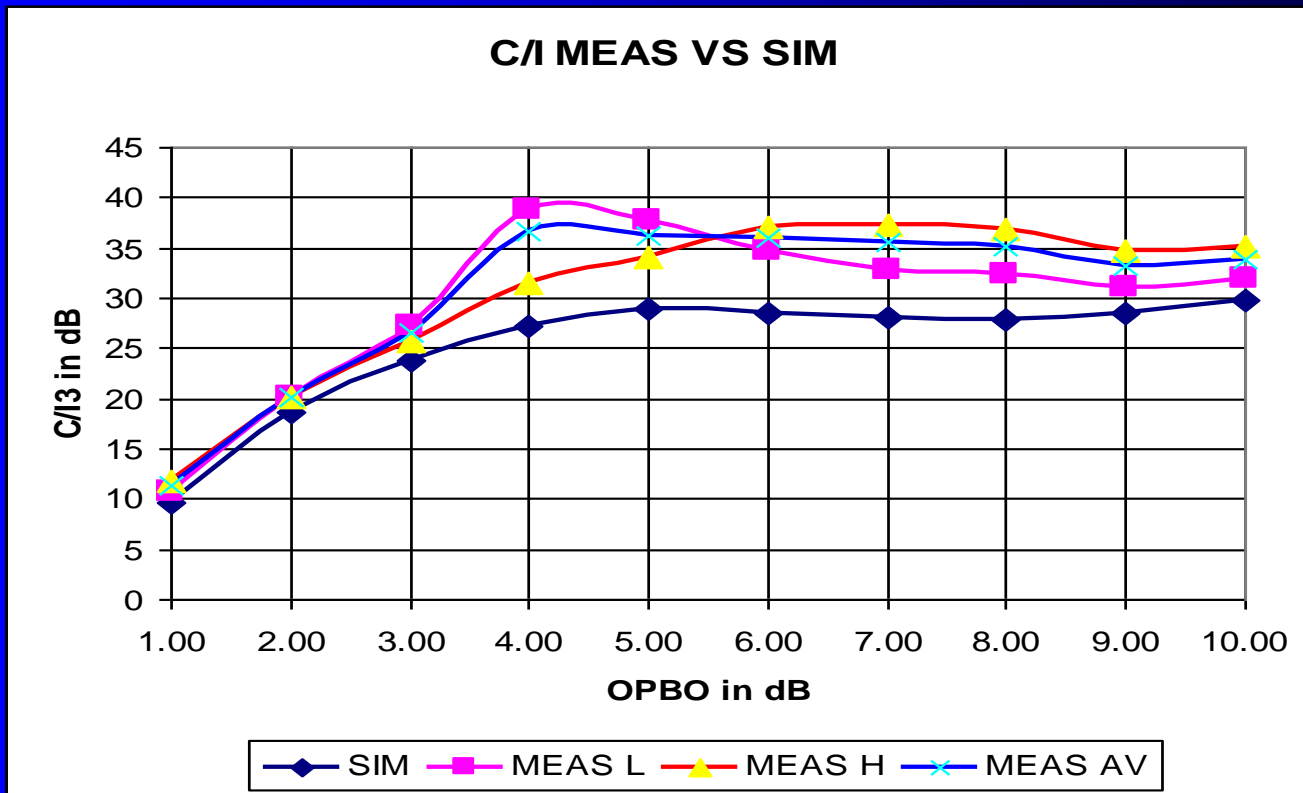
Change in drain voltage amplitude modulates and phase modulates the PA output producing sidebands at the same frequencies as intermodulation distortion (IMD)

# IMD NON-SYMMETRY



Non-symmetrical IMD products can result from the interaction of device and drain / gate ripple induced IMD (simplest test for PA memory effects)

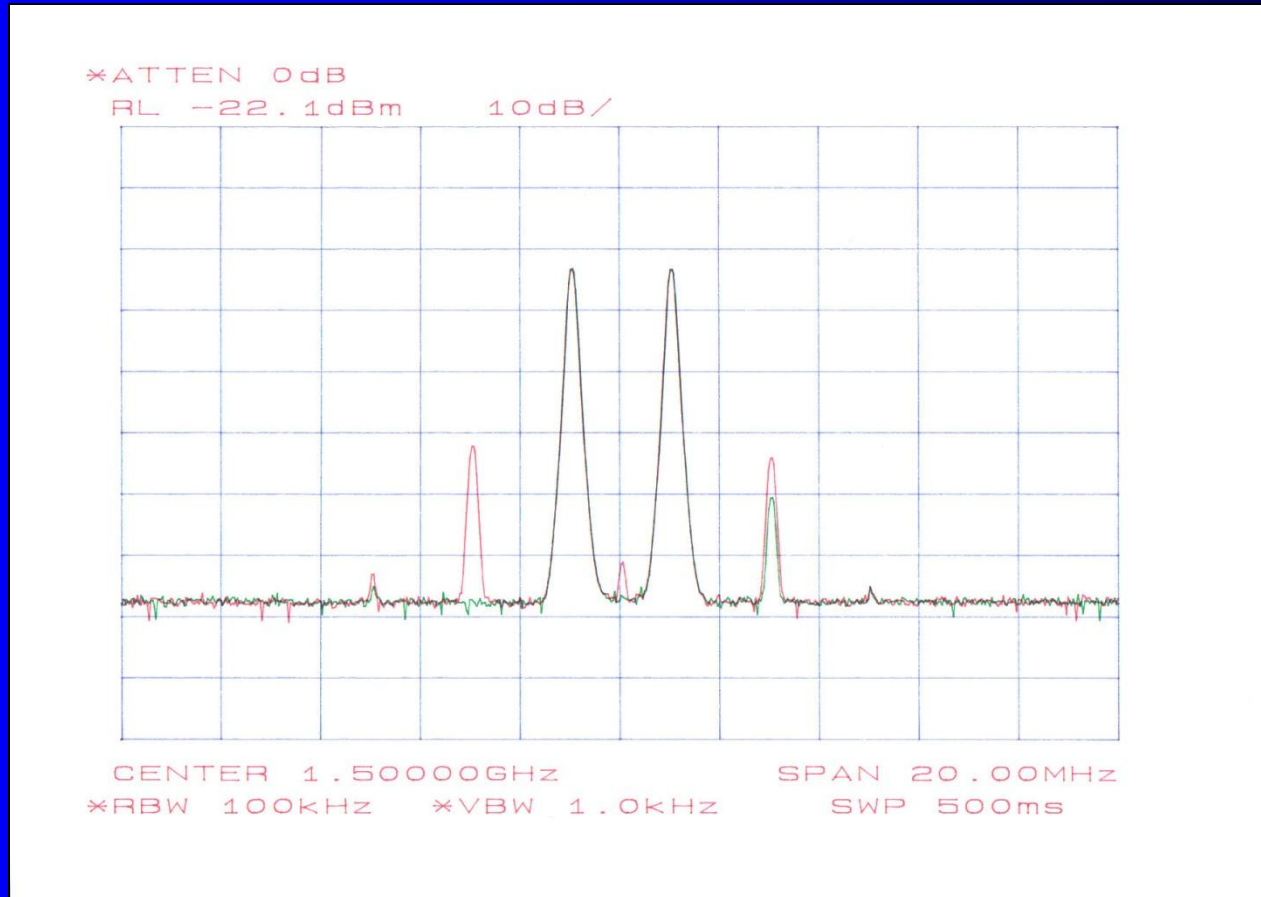
# IMD NON-SYMMETRY



Overall carrier to interference (C/I) ratio can be higher than expected based on the PA transfer characteristics

This effect is the result of IMD cancellation

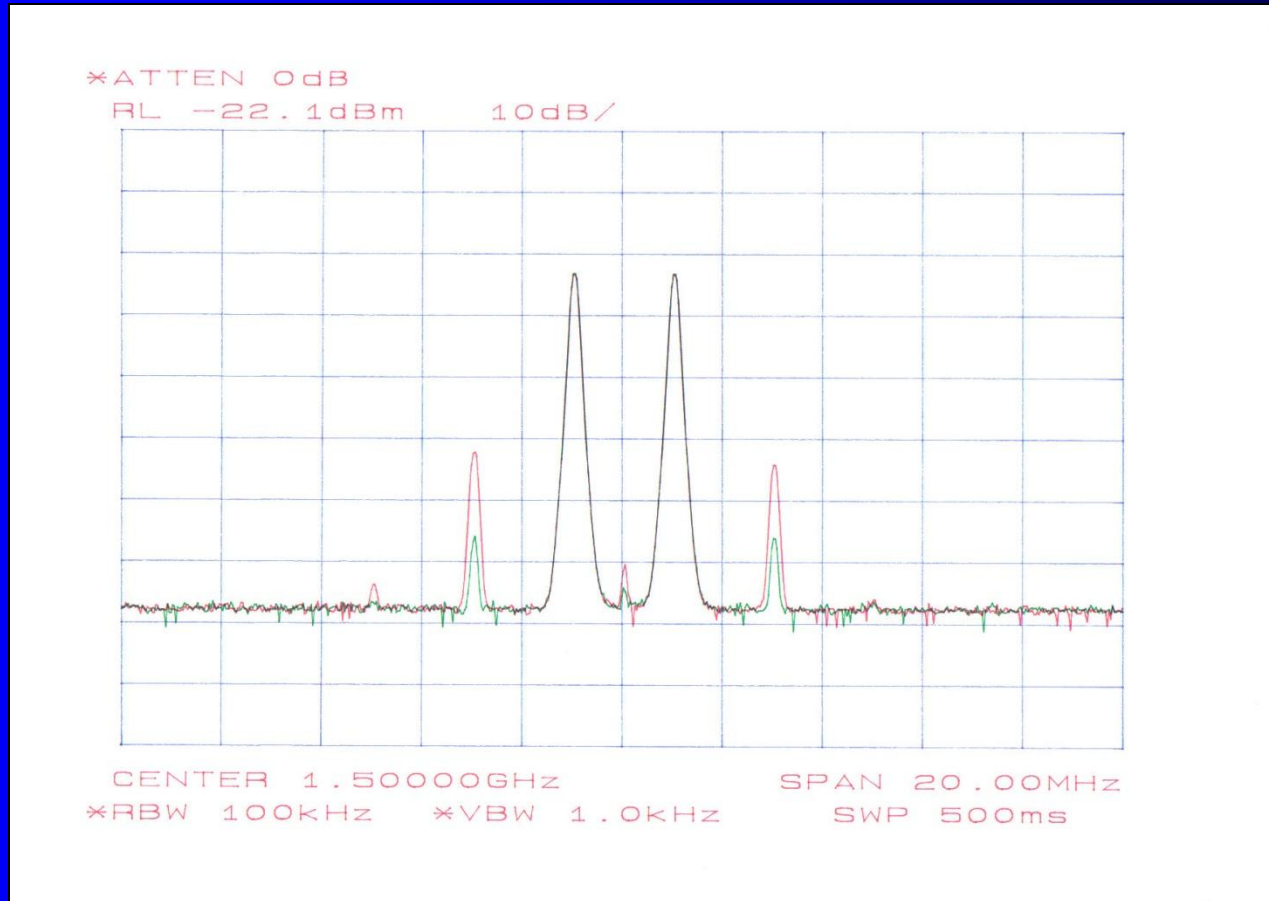
# IMD NON-SYMMETRY



**Memory effects produce non-even cancellation of IMD**

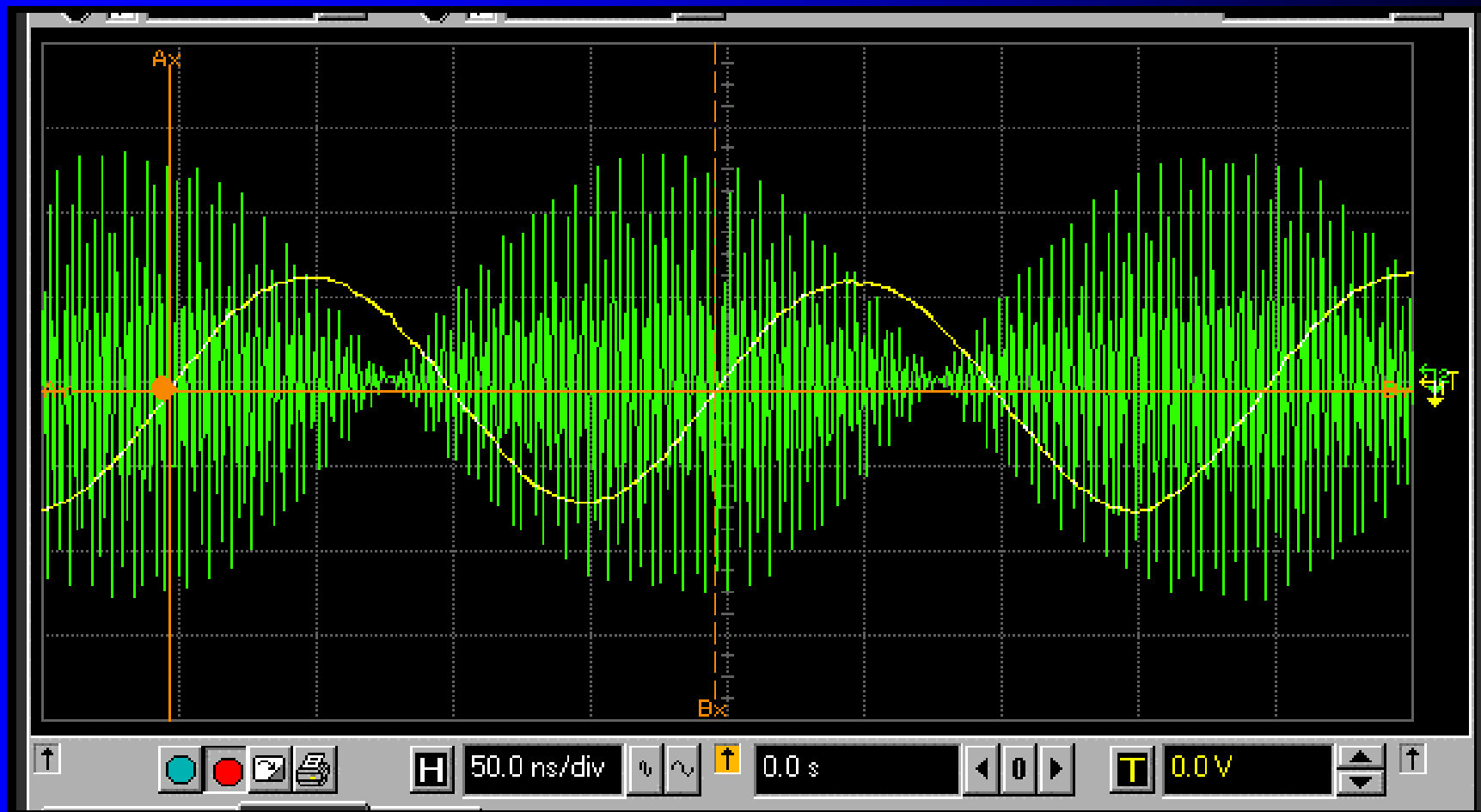


# IMD NON-SYMMETRY



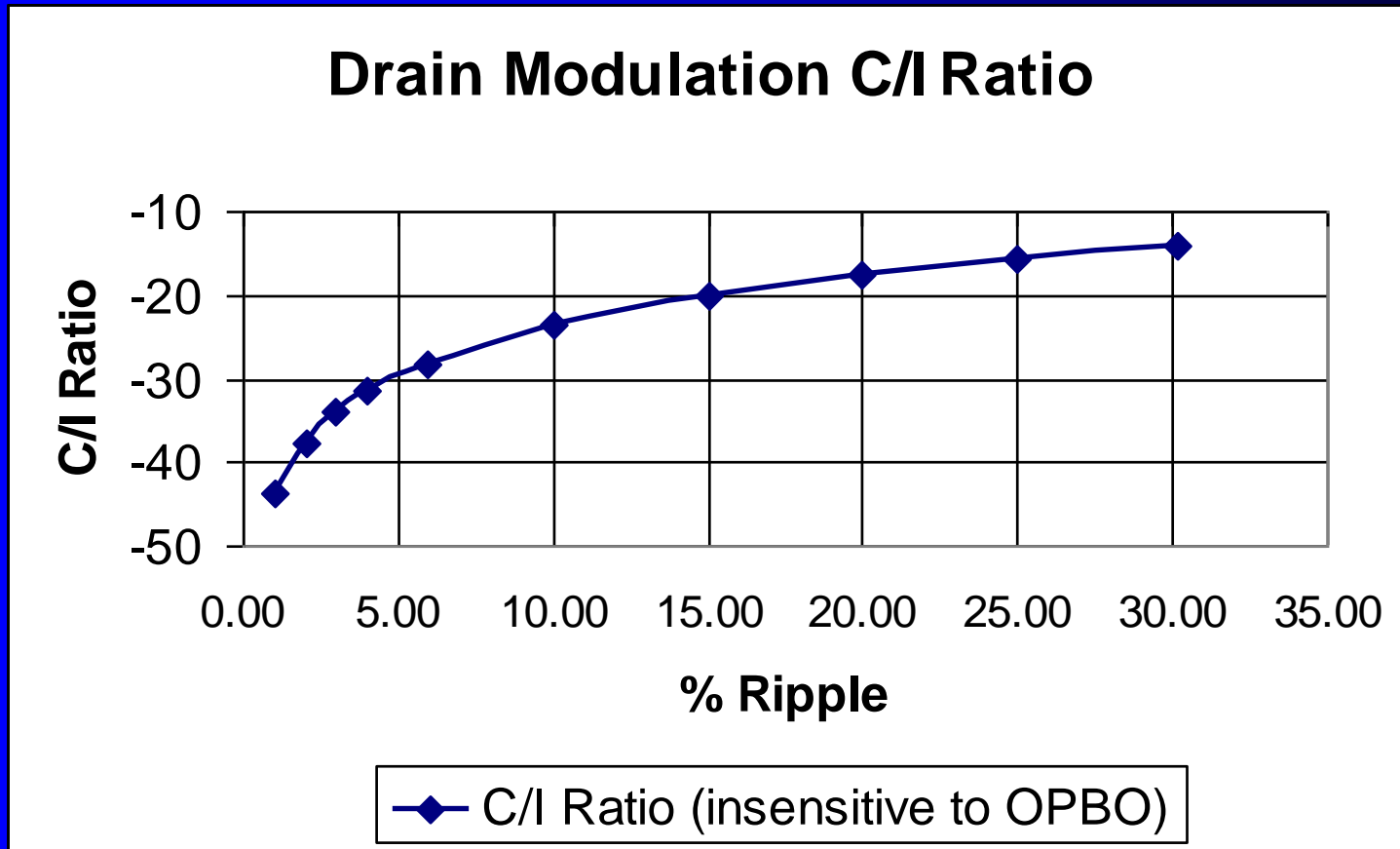
**Compromise IMD cancellation can be achieved, but may not be sufficient**

# RF ENVELOPE (GREEN) IS $\sim 140^\circ$ OUT OF PHASE WITH DRAIN RIPPLE (YELLOW)



IMDs caused by the PA non-linearity subtract from the ripple induced IMDs

# DRAIN/COLLECTOR MEMORY EFFECTS



Measurement of the sensitivity of a GaAs FET PA to drain modulation

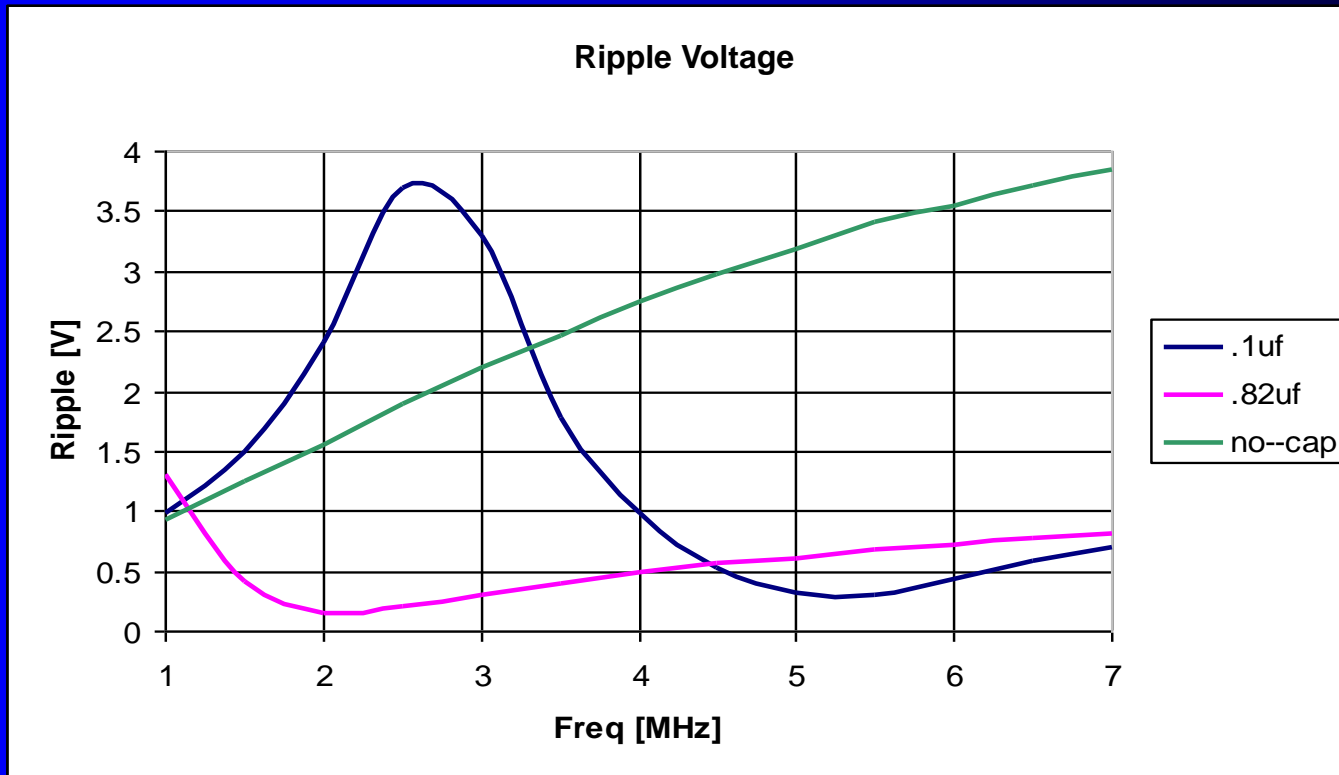
Ripple < 2% is required for C/I < 40 db

# DRAIN/COLLECTOR MEMORY EFFECTS



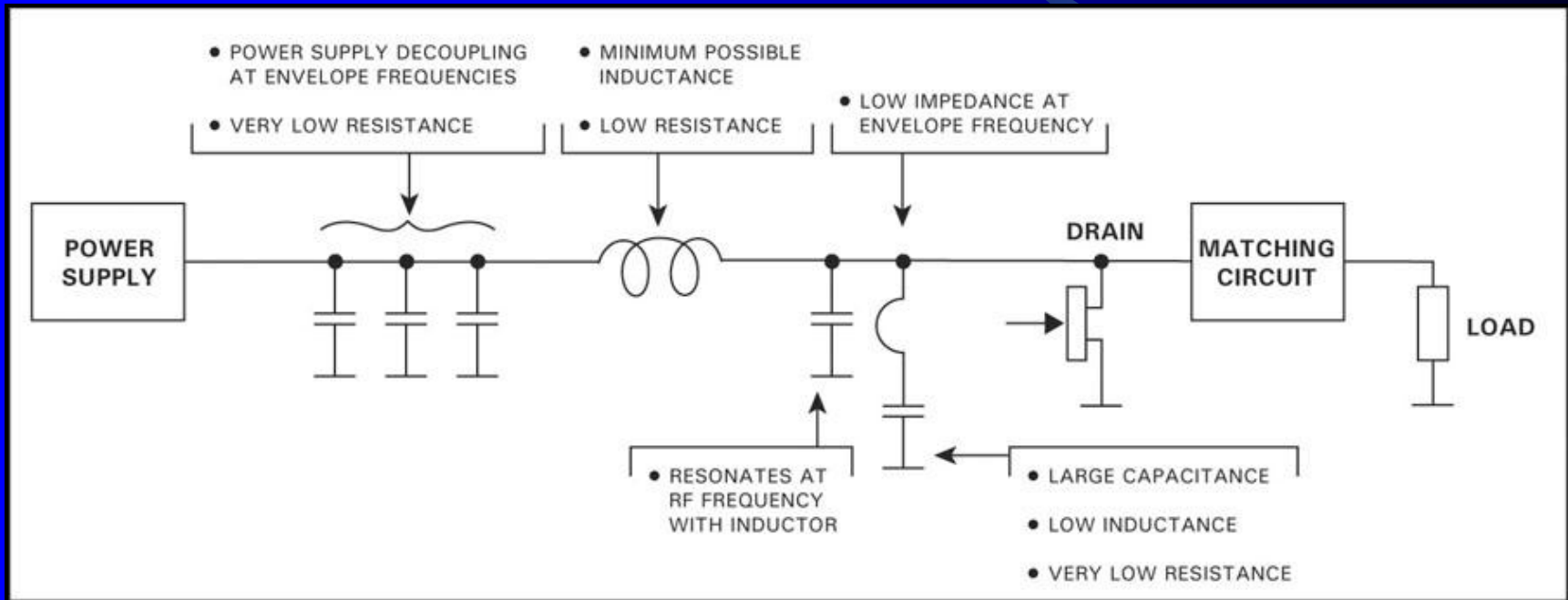
Amplifier linearity can change and often degrades with increasing carrier spacing

# DRAIN/COLLECTOR MEMORY EFFECTS



- For wide or even moderate bandwidth signals, the drain ripple is not a trivial problem
- Consider a 250 MHz PA with a 25 MHz multi carrier signal

# DRAIN/COLLECTOR MEMORY EFFECTS MINIMIZATION

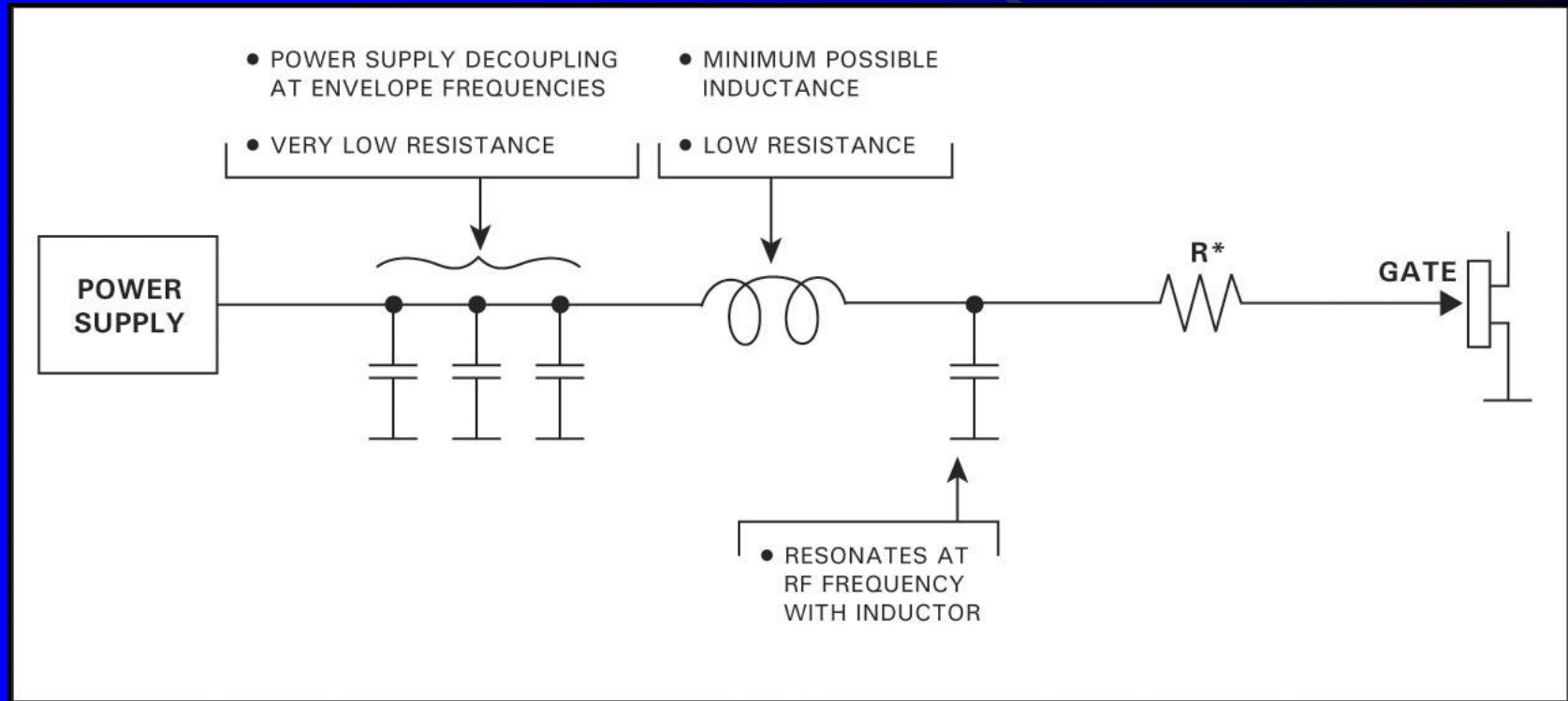


A low impedance network at envelope frequencies across the drain and effective power supply decoupling can minimize memory effects

# GATE/BASE MEMORY EFFECTS

- Change in gate (or base) voltage can also be a significant contributor to memory effects
- This problem can be more difficult to solve than for the drain / collector case, and is quite different for BJT and FET devices
- PA stability can be a major concern
- Low currents are involved, so good power supply decoupling is easier to achieve
- GaAs FET gate supply must achieve good voltage regulation in spite of current flowing due to RF rectification by the gate-source diode

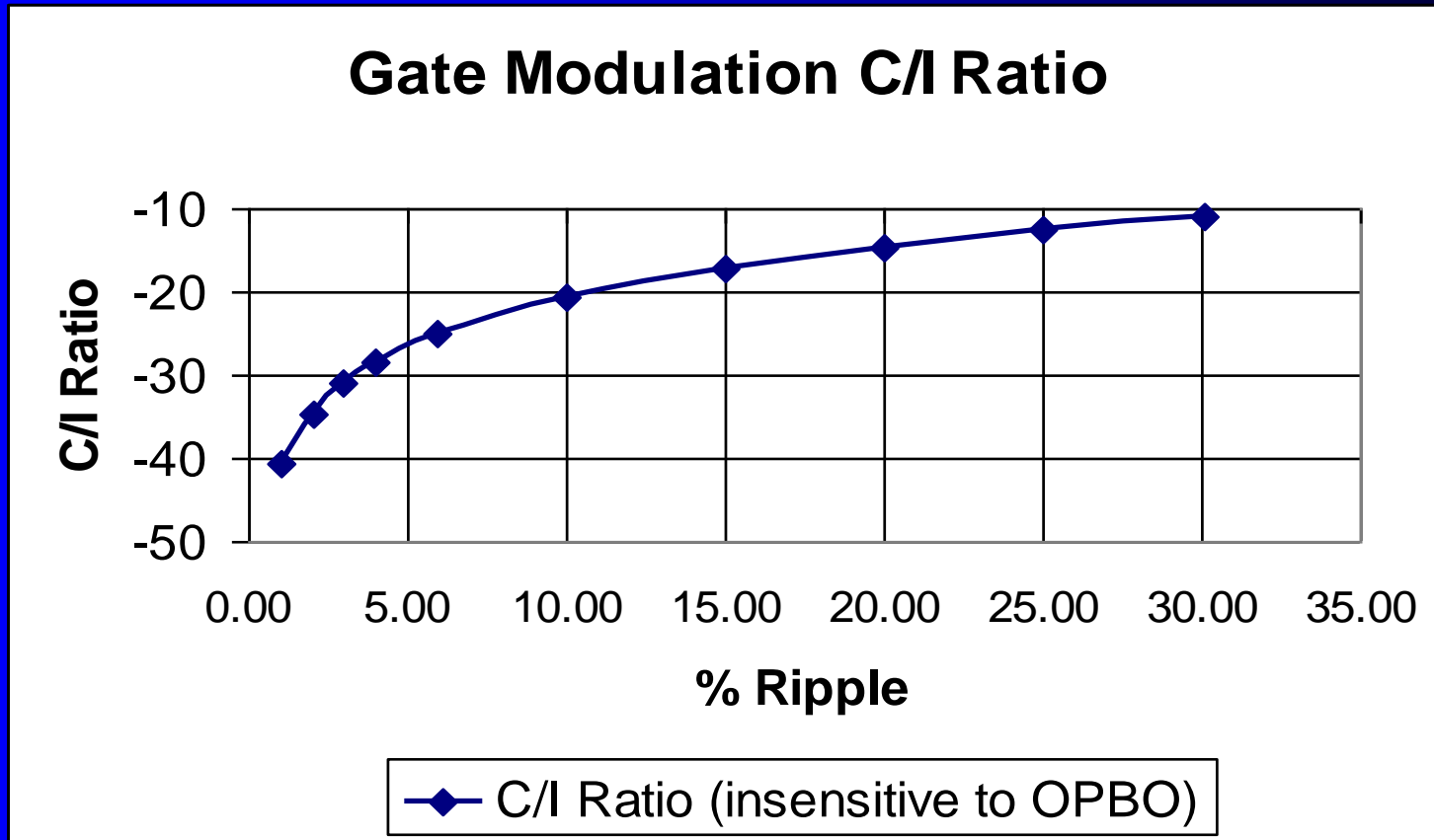
# GATE MEMORY EFFECTS MINIMIZATION



The value of  $R^*$  must be carefully chosen to provide a compromise between stability and bias-induced memory effects



# GATE MEMORY EFFECTS



Measurement of the sensitivity of a GaAs FET PA to gate modulation

Ripple < 1% is required for C/I < 40 db

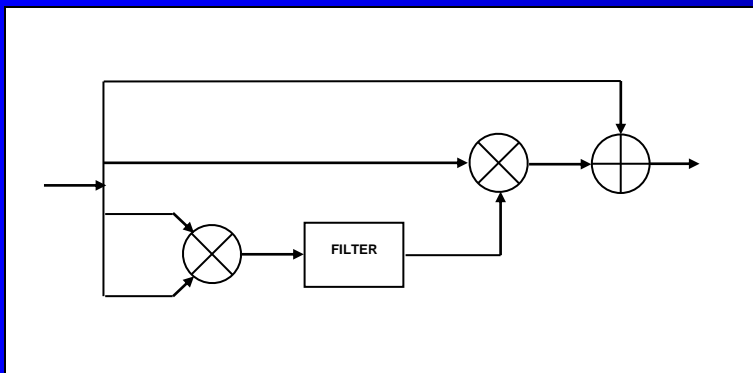
# THERMAL MEMORY EFFECTS

- Major source of thermal memory effects is device junction temperature changes as a function of envelope frequency, particularly below 100 KHz
- Choice of device can minimize temperature memory effects. Temperature affects some devices less
- Bias class can also minimize temperature effects. Class A is less affected than class B, but has low efficiency
- Long term temperature changes (that do not depend on the envelope frequency) can also be considered a memory effect. Good thermal design or an adaptive circuitry can minimize this problem

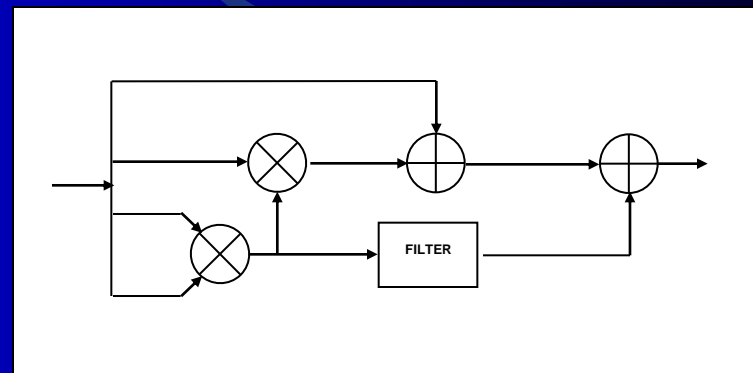
# DEVICE RELATED MEMORY EFFECTS

- Some devices display changes in non-linear characteristics with envelope frequency that cannot be explained by bias modulation
- This phenomena appears related to current flow and charge trap build up. Some sources have attributed it to very small time-constant thermal effects
- Different devices show varying sensitivity. HBT, some LDMOS and GaN devices appear particularly sensitive
- No recommended solution except careful device selection

# ADDITIONAL MEMORY EFFECTS CANCELLATION METHODS



Envelope Filtering



Envelope Injection

These methods are covered in the book “Distortion in RF Power Amplifiers” by J. Vuolevi and T. Rahkonen

# Summary

- It is difficult to eliminate distortion caused by MEs using linearization
- Bias voltage variations (both drain/collector and gate/base) are a major cause of MEs
- Thermal change is another important source of MEs
- MEs can be minimized by careful electrical and mechanical design

# Where to Get More Information

Vuolevi and Rahkonen, “Distortion in RF Power Amplifiers”, Artech House, 2003.

Cripps, “RF Power Amplifiers for Wireless Communications”, Artech House, 1999.

Cripps, “Advanced Techniques in RF Power Amplifier Design”, Artech House, 2002.

W. Bosch, G. Gatti, “Measurement and Simulation of Memory Effects in Predistortion Linearizers”, IEEE Transactions on Microwave Theory and Techniques, Vol. 37, No. 12, December 1989.

A. Katz, “Linearization: Reducing Distortion in Power Amplifiers”, IEEE Microwave Magazine, December 2001.

S. Boumaiza, F. Ghannouchi, “Thermal Memory Effects Modeling and Compensation in RF Power Amplifiers and Predistortion Linearizers”, IEEE MTT, December 2003.

K. Cho, J. Choi, J. Kim, B. Lee, N. Kim, J. Lee, S. Stapleton, “An Analog Compensation Method for Asymmetric IMD Characteristics of a Power Amplifier”, 2003 IEEE MTT-S Digest.

H. Ku, J. Kenney, “Behavioral Modeling of RF Power Amplifiers Considering IMD and Spectral Regrowth Asymmetries”, 2003 IEEE MTT-S.

N. Borges de Carvalho, J. Pedro, “A Comprehensive Explanation of Distortion Sideband Asymmetries”, IEEE MTT, September 2002.